

Title (en)

MAGNETORESISTIVE STRUCTURE WITH ALLOY LAYER

Title (de)

MAGNETORESISTIVE STRUKTUR MIT EINER LEGIERUNGSSCHICHT

Title (fr)

STRUCTURE MAGNETORESISTIVE A COUCHE D'ALLIAGE

Publication

EP 0678213 B1 20030219 (EN)

Application

EP 94901337 A 19931108

Priority

- US 9310782 W 19931108
- US 97690592 A 19921116

Abstract (en)

[origin: WO9411889A1] A magnetoresistive layered structure having a pair of magnetoresistive, anisotropic ferromagnetic thin-films (F'1, F'2) separated by an intermediate layer (l'1) on a substrate (10, 11) of less than 50 ANGSTROM thickness formed of a substantially nonmagnetic, conductive alloy having two immiscible components therein.

IPC 1-7

H01F 1/00; B32B 15/00; B32B 15/20; B32B 9/00; G11B 5/127; G11B 5/147; G01R 33/02; H01L 43/10; H01F 10/08

IPC 8 full level

G01R 33/09 (2006.01); **G11B 5/39** (2006.01); **H01F 10/08** (2006.01); **H01F 10/30** (2006.01); **H01F 10/32** (2006.01); **H01L 21/8246** (2006.01); **H01L 27/22** (2006.01); **H01L 43/08** (2006.01); **H01L 43/10** (2006.01)

CPC (source: EP US)

B82Y 10/00 (2013.01 - EP US); **B82Y 25/00** (2013.01 - EP US); **G01R 33/093** (2013.01 - EP US); **G11B 5/3903** (2013.01 - EP US); **G11B 5/3945** (2013.01 - EP US); **G11B 5/3948** (2013.01 - EP US); **H01F 10/324** (2013.01 - EP US); **H01F 10/325** (2013.01 - EP US); **H10N 50/10** (2023.02 - EP US); **H10N 50/85** (2023.02 - EP US); **G11B 2005/3996** (2013.01 - EP US); **Y10S 428/90** (2013.01 - EP US); **Y10S 428/928** (2013.01 - EP US); **Y10T 428/1157** (2015.01 - EP US); **Y10T 428/12465** (2015.01 - EP US); **Y10T 428/12632** (2015.01 - EP US); **Y10T 428/12903** (2015.01 - EP US); **Y10T 428/1291** (2015.01 - EP US); **Y10T 428/12931** (2015.01 - EP US)

Citation (examination)

EDITORS H OKAMOTO ET AL: "Binary alloy phase diagrams, 2nd Edition, Pages 358-361", 1990, WILLIAM W SCOTT JR, ASM INTERNATIONAL, MATERIALS PARK, OHIO, US

Designated contracting state (EPC)

DE FR GB IT NL

DOCDB simple family (publication)

WO 9411889 A1 19940526; DE 69332699 D1 20030327; DE 69332699 T2 20030918; EP 0678213 A1 19951025; EP 0678213 A4 19951108; EP 0678213 B1 20030219; JP H08503336 A 19960409; US 5595830 A 19970121

DOCDB simple family (application)

US 9310782 W 19931108; DE 69332699 T 19931108; EP 94901337 A 19931108; JP 51227794 A 19931108; US 23232494 A 19940425